

# MUR2020CT

Rev.G Oct.-2018

## / Descriptions

TO-220

Ultrafast Recovery Diode in a TO-220 Plastic Package.

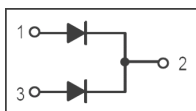
## / Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

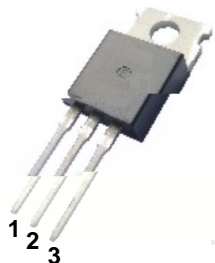
## / Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode.

## / Equivalent Circuit



## / Pinning



PIN1 Anode

PIN 2 Cathode

PIN 3 Anode

## / h<sub>FE</sub> Classifications & Marking

See Marking Instructions

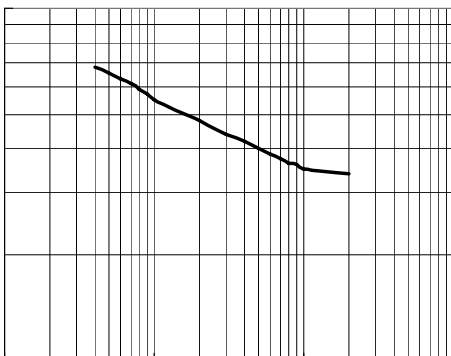
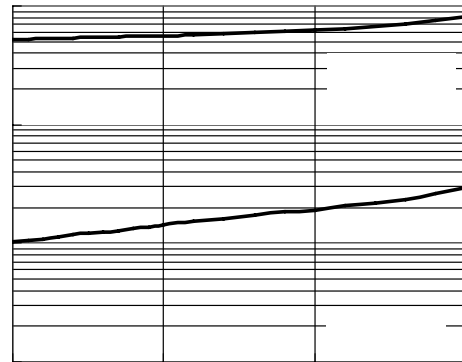
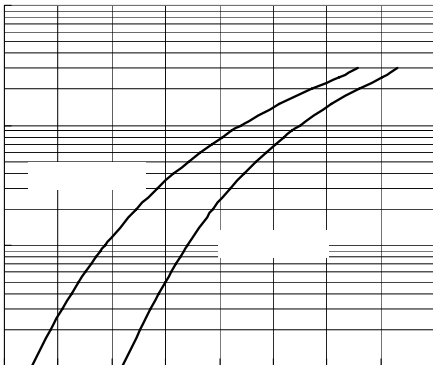
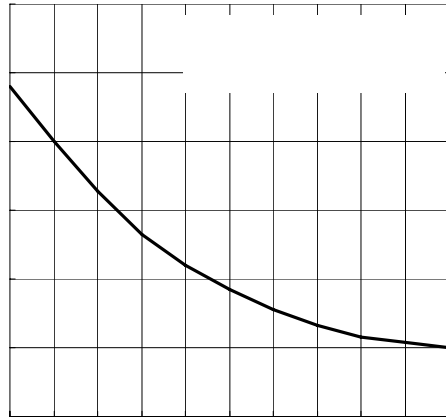
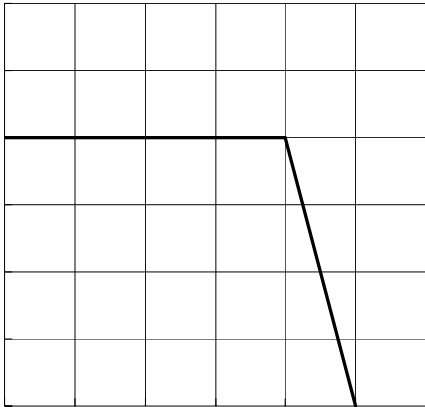
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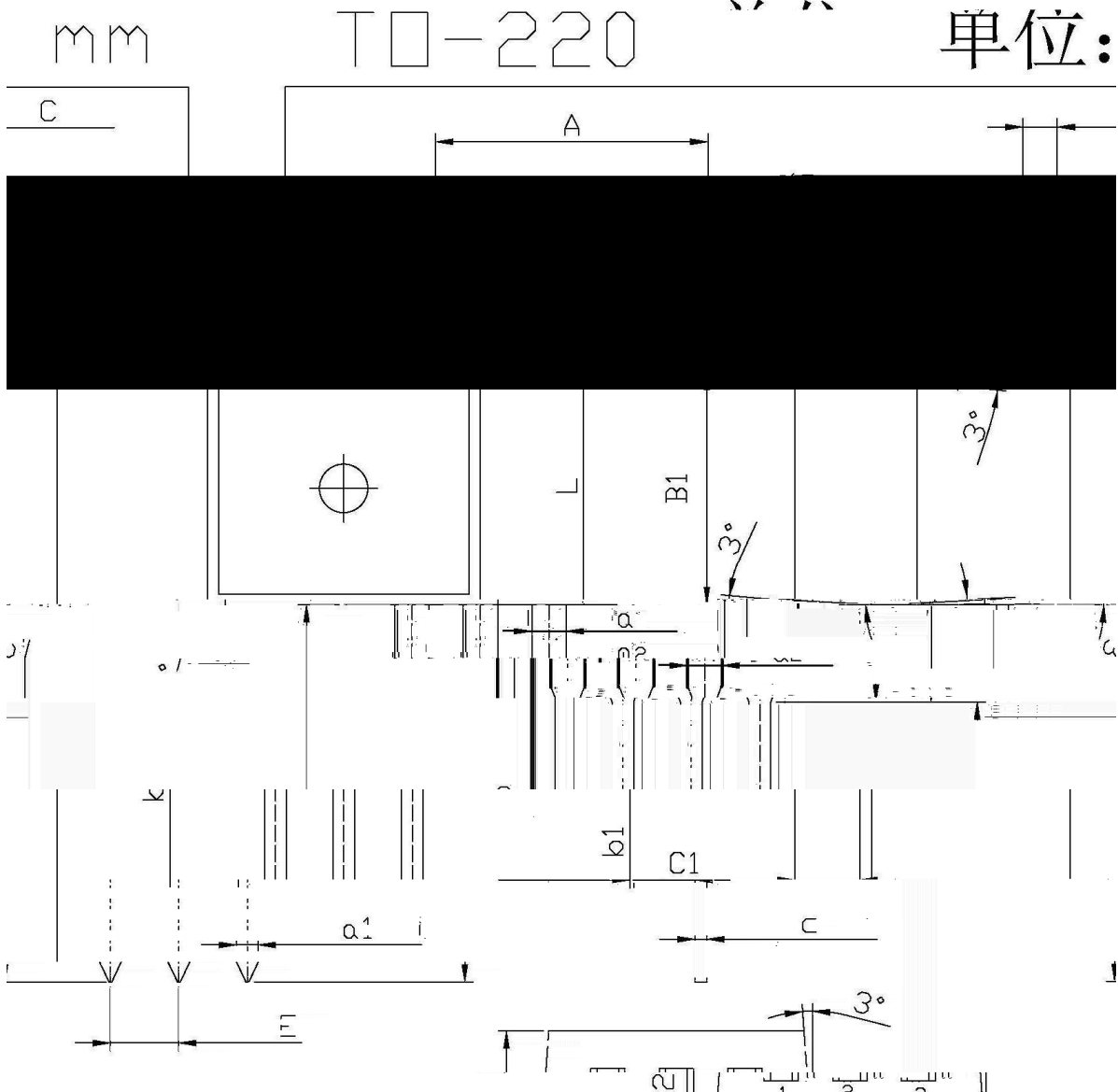
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	200	V
RMS Voltage	$V_{RMS}$	140	V
DC Blocking Voltage	$V_{DC}$	200	V
Average Forward Current	$I_F$	2 10	A
Non Repetitive Peak Surge Current	$I_{FSM}$	120	A
Thermal Resistance Junction to Case	$R_{Jc}$	2.8	/W
Operating and Storage Temperature Range	$T_j$ $T_{stg}$	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	$V_F$	$I_F=2A$ $T_c=25$		0.79		V
		$I_F=2A$ $T_c=125$				

/ Electrical Characteristic Curve

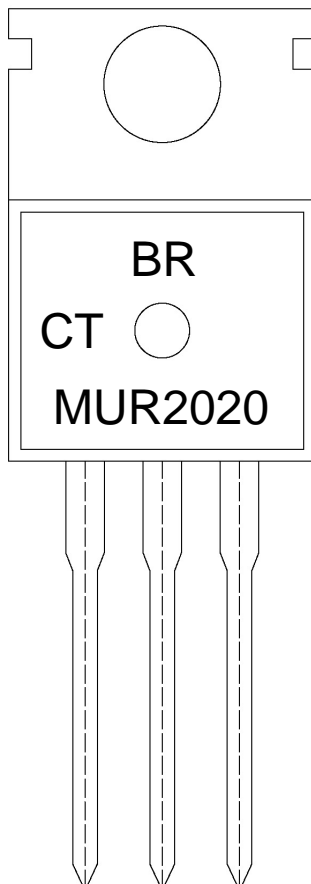


/ Package Dimensions



Symbol	Dimensions in milimeters		Symbol	Dimensions in millimeters	
	Min	Max		Min	Max
A	9.8	10.2	C	1.2	1.4
B	3.56	3.64	B1	6.3	6.7
B1	9.0	9.4	L	15.7	16
C1	2.2	2.6	b1	12.6	13
a1	0.7	0.9	h1	9.6	10
c	0.4	0.6	a	1.22	1.32
φ	1.45	1.7	φ	0.2	1.25

/ Marking Instructions



BR

MUR2020

CT:

\*\*\*\*

Note:

BR: Company Code

MUR2020 Product Type.

CT: Internal Structure

\*\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- |   |       |     |           |        |   |
|---|-------|-----|-----------|--------|---|
| 1 | 25    | 150 | 60        | 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 255±5 |     | 5±0.5sec; |        | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10        | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

270±5                      10±1 sec.                      Temp.:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	只套管	套管盒	只盒	盒箱	只箱	套管	盒	箱

/ Notices